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**Universal serial bus interfaces for data and power –
Part 1-2: Common components – USB Power Delivery specification**

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Part 1-2: Common components – USB Power Delivery specification

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The text of this standard was prepared by the USB Implementers Forum (USB-IF). The structure and editorial rules used in this publication reflect the practice of the organization which submitted it.

The text of this standard is based on the following documents:

CDV	Report on voting
100/2728/CDV	100/2729/RVC

Full information on the voting for the approval of this International Standard can be found in the report on voting indicated in the above table.

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WITHDRAWN

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The IEC 62680 series is based on a series of specifications that were originally developed by the USB Implementers Forum (USB-IF). These specifications were submitted to the IEC under the auspices of a special agreement between the IEC and the USB-IF.

This standard is the USB-IF publication USB Power Delivery Specification Revision 3.0 V.1.0.

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Universal Serial Bus Power Delivery Specification

Revision 3.0, V1.0. 11 December 2015

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